

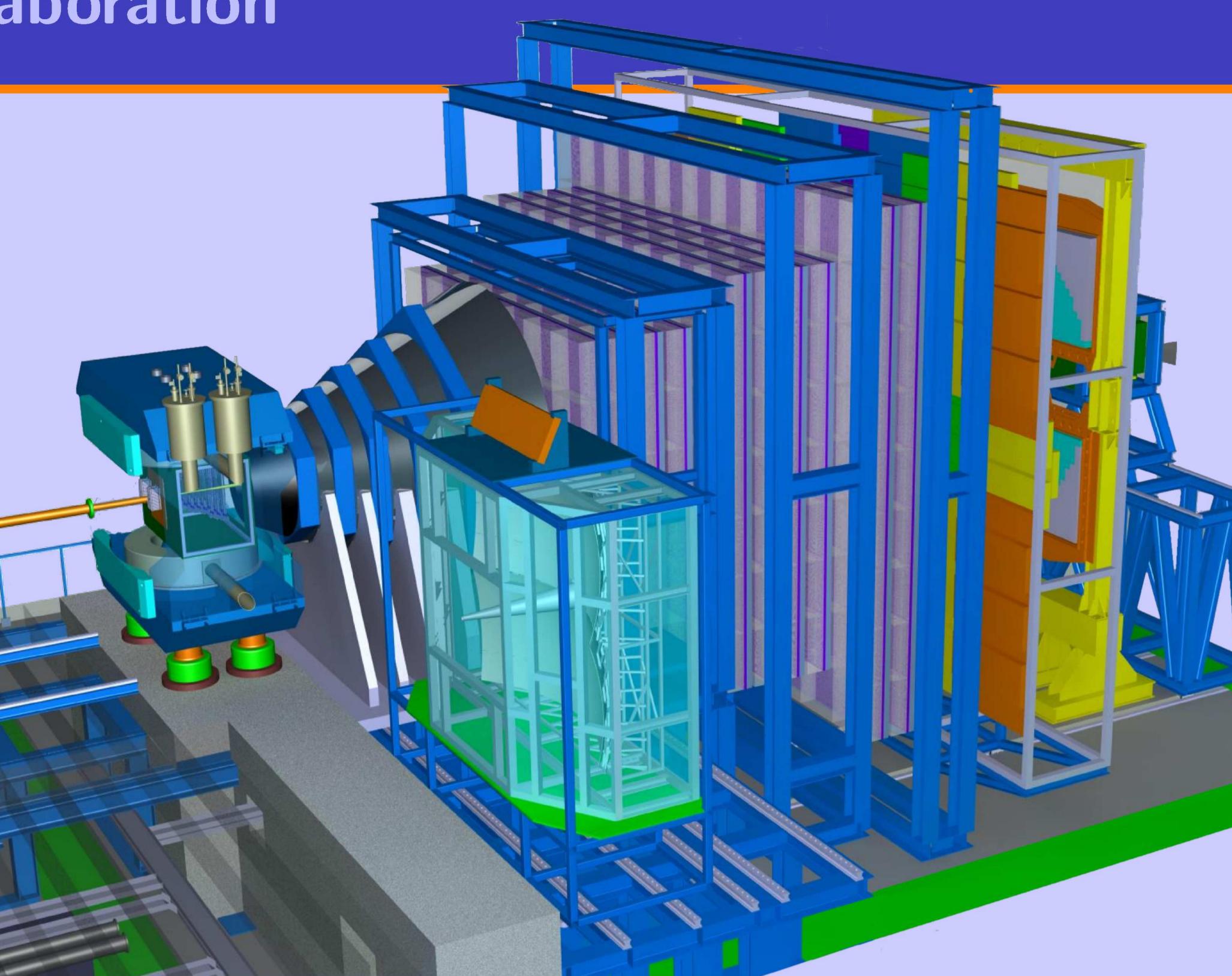
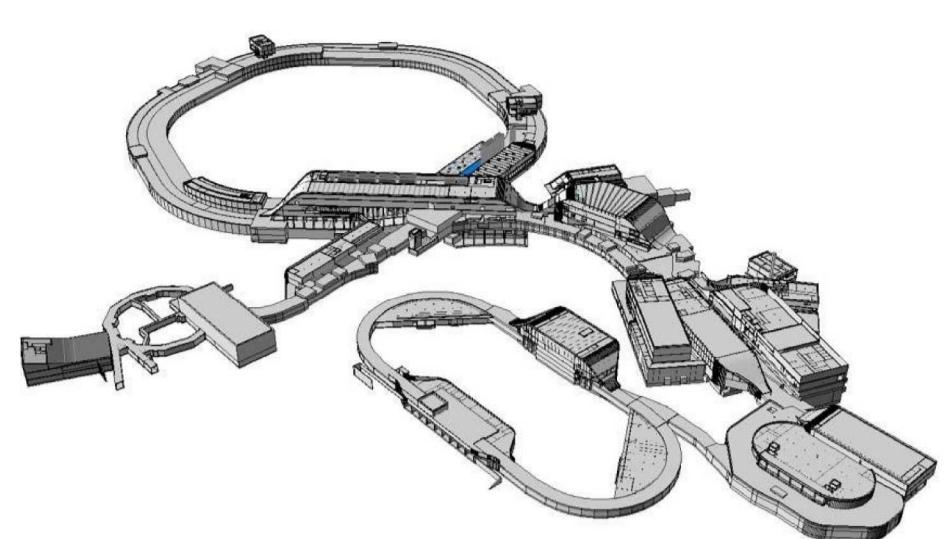
# Silicon Tracking System for the CBM experiment at FAIR

Maksym Teklishyn<sup>1,2</sup> for the CBM Collaboration

## Experimental facilities

### FAIR research complex

- Primary beams
  - $10^{12}/\text{s}$ , 1.5 GeV,  $^{238}\text{U}^{28+}$
  - $10^{10}/\text{s}$ ,  $\lesssim 35$  GeV,  $^{238}\text{U}^{73+}$
- Secondary beams (including radioactive and antiprotons)
- Accelerators:
  - SIS18 (*existing*)
  - SIS100 (*to be constructed, scheduled on early 2020-s*)
  - Total synchrotron length (including beamlines) 1.1 km (3.2 km)
- Experiments:
  - APPA
  - NUSTAR
  - PANDA
  - CBM** — dedicated for the Quark-Gluon Plasma studies
    - fixed target (Au-Au collisions)
    - high-rate experiment ( $\lesssim 10\text{MHz}$ )
    - electron/muon configuration for systematics crosscheck
    - extreme density/temperature

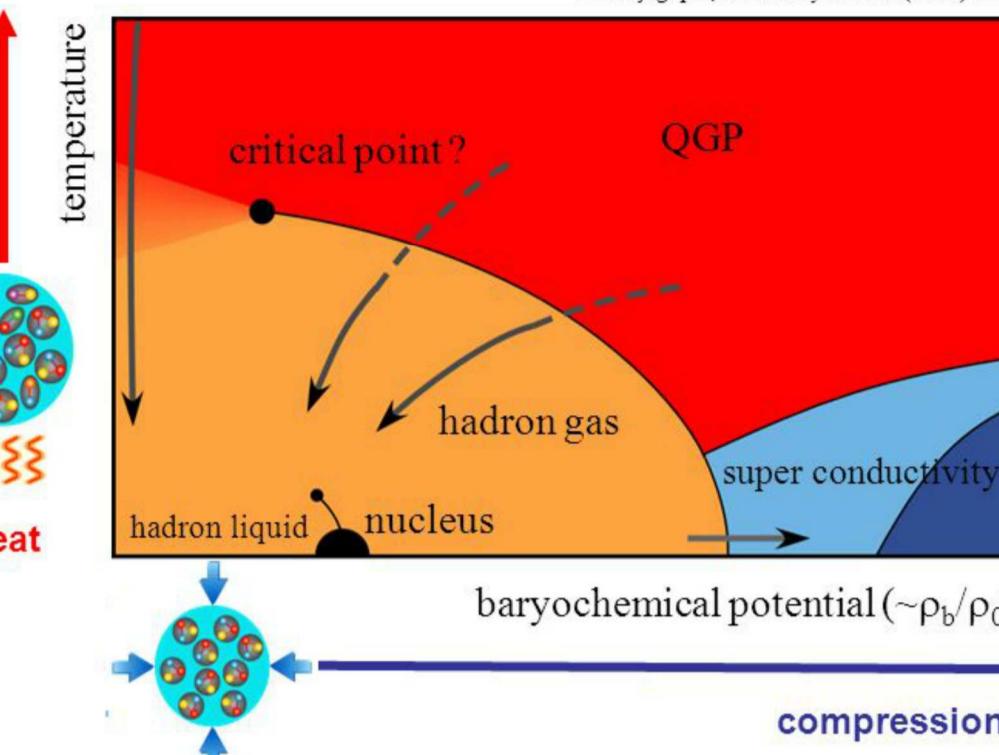


### CBM tracking setup:

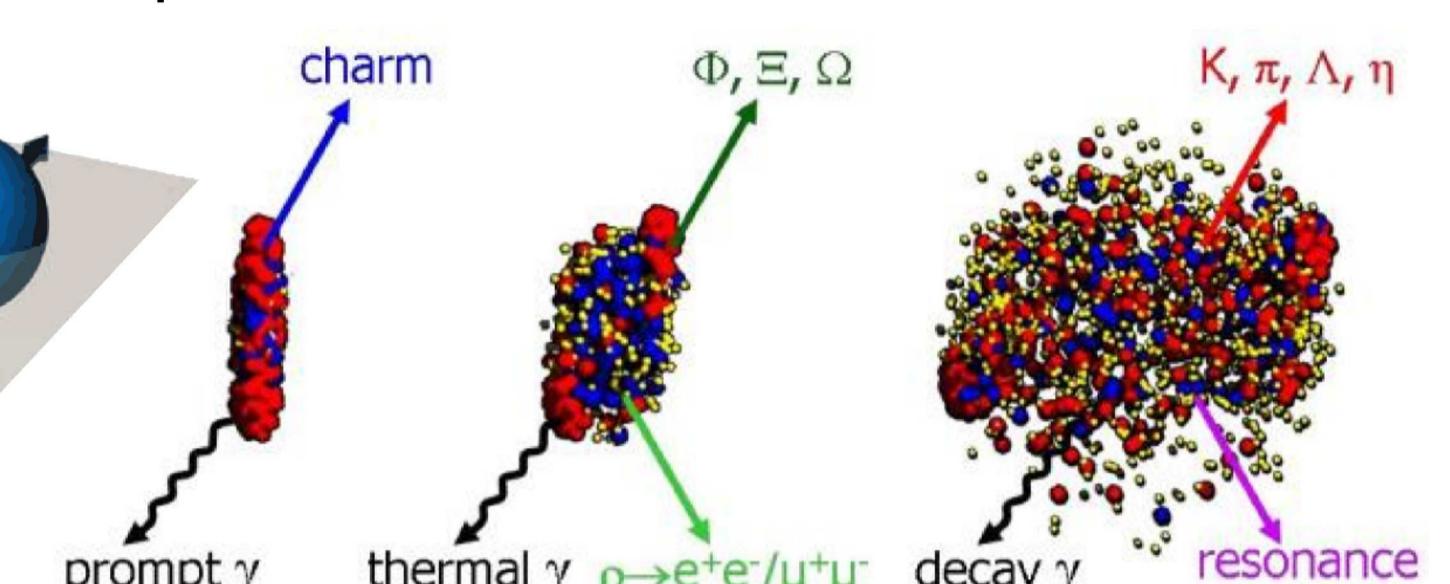
- Micro Vertex Detector for interaction vertex positioning
- Silicon Tracking System
- Inside 1 Tm dipole magnet (momentum measuring)
- MuCh, RICH, TRD, ToF, PSD and ECAL subdetectors

## Physics motivation

K Rajagopal, Nucl. Phys. A661 (1999) 150



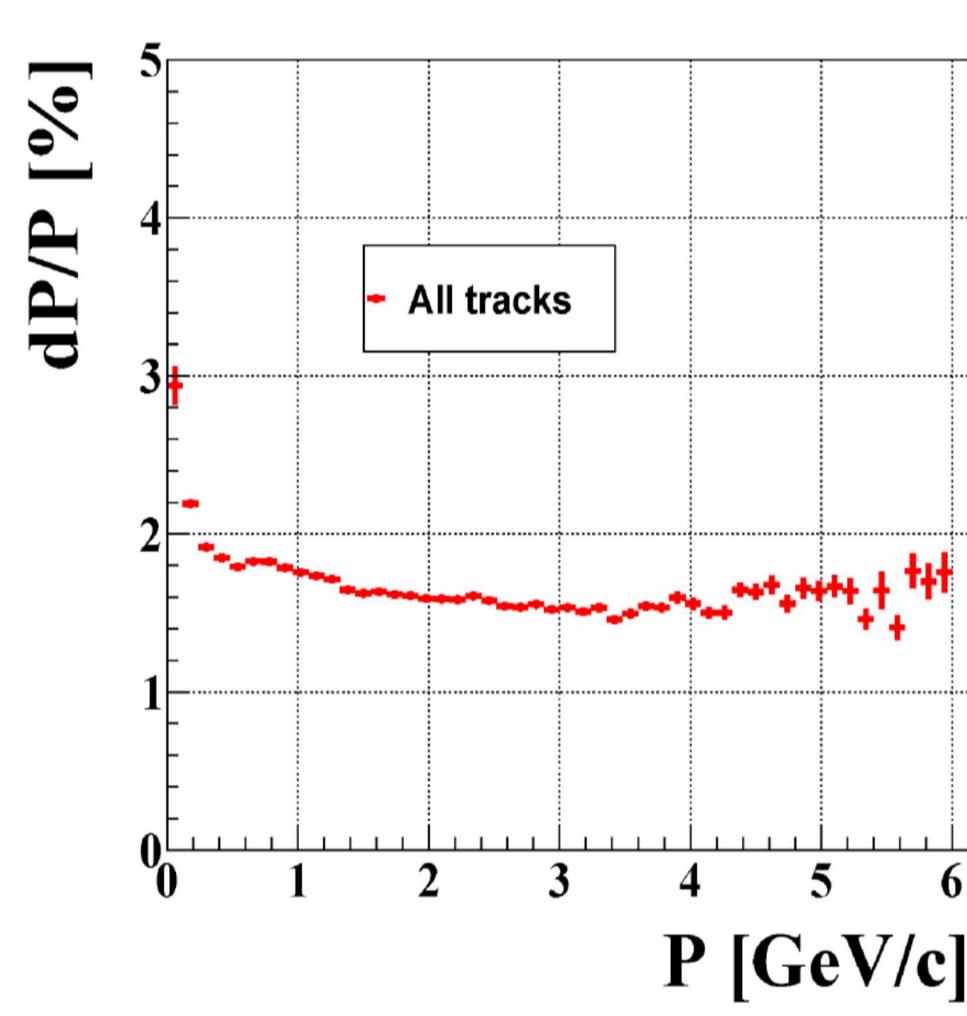
Does the first order phase transition exist?



(Quasi)stable particles are observed:  $e^\pm, \mu^\pm, K, \pi, \gamma,$

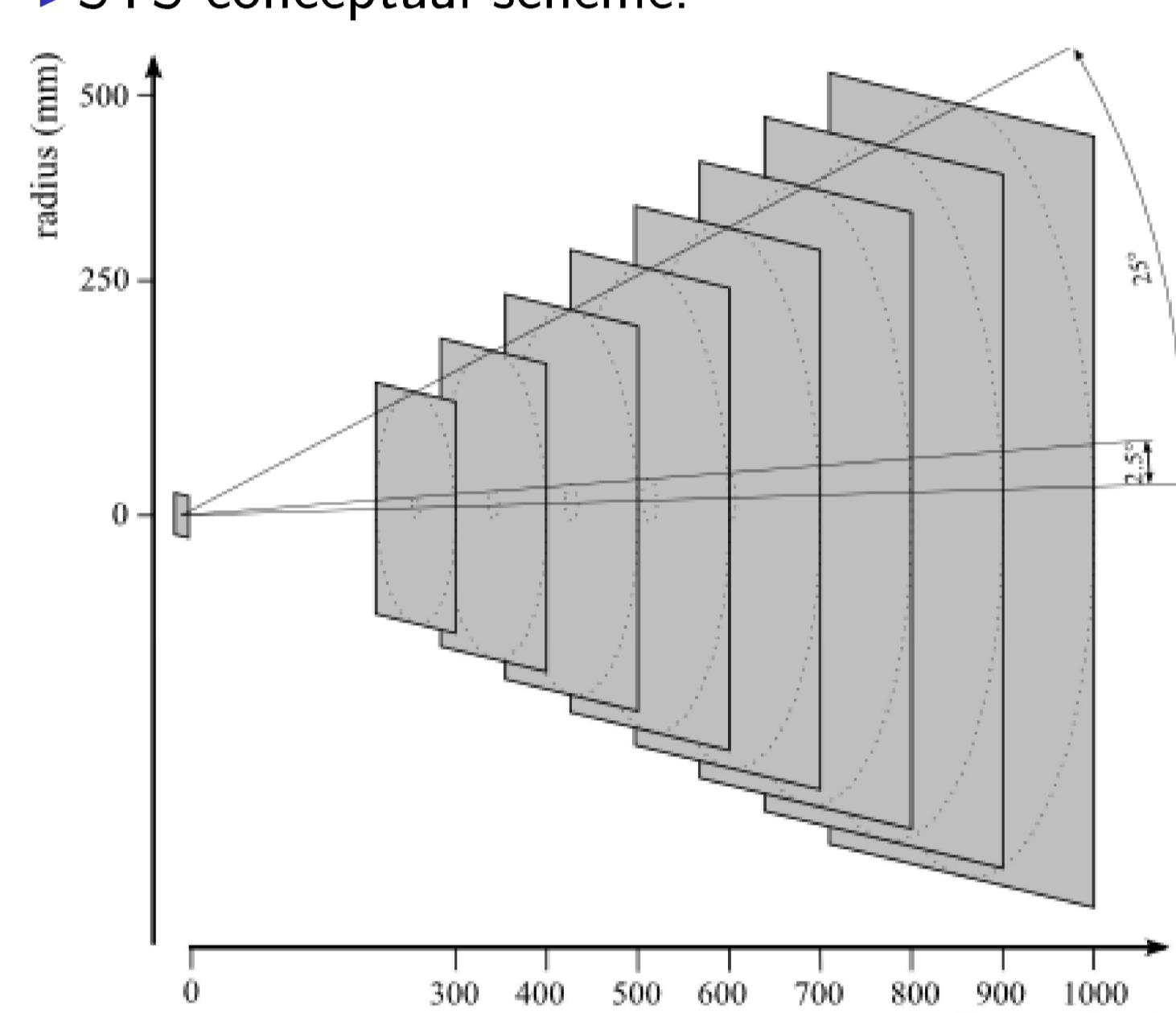
## Silicon Tracker System design

- Detector acceptance
  - rapidities from centre-of-mass to beampipe
  - angular coverage  $2.5^\circ < \Theta < 25.0^\circ$
- Low mass large area detector
  - readout electronics shifted away from the acceptance region
  - double sided  $300\text{ }\mu\text{m}$  thick silicon sensors (8 stations)
  - material budget per station  $\simeq 1\% X_0$
  - low scattering, high momentum resolution
  - track matching in MVD and RICH/MUCH
- Momentum resolution
  - $\Delta p/p \simeq 1.5\%$
  - up to  $\simeq 25\text{ }\mu\text{m}$  single hit resolution



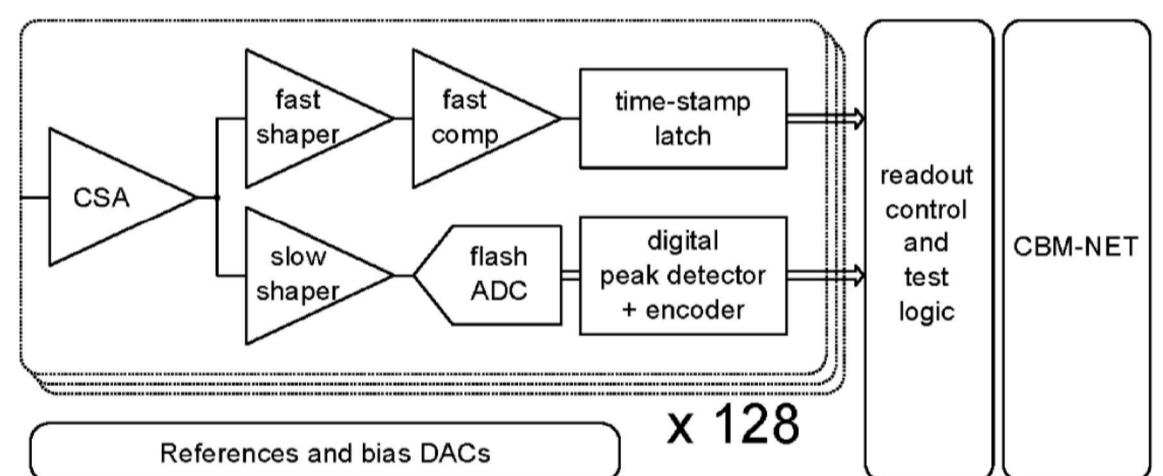
- Efficiency
  - track and single hit reconstruction efficiency  $\simeq 100\%$

### STS conceptual scheme:



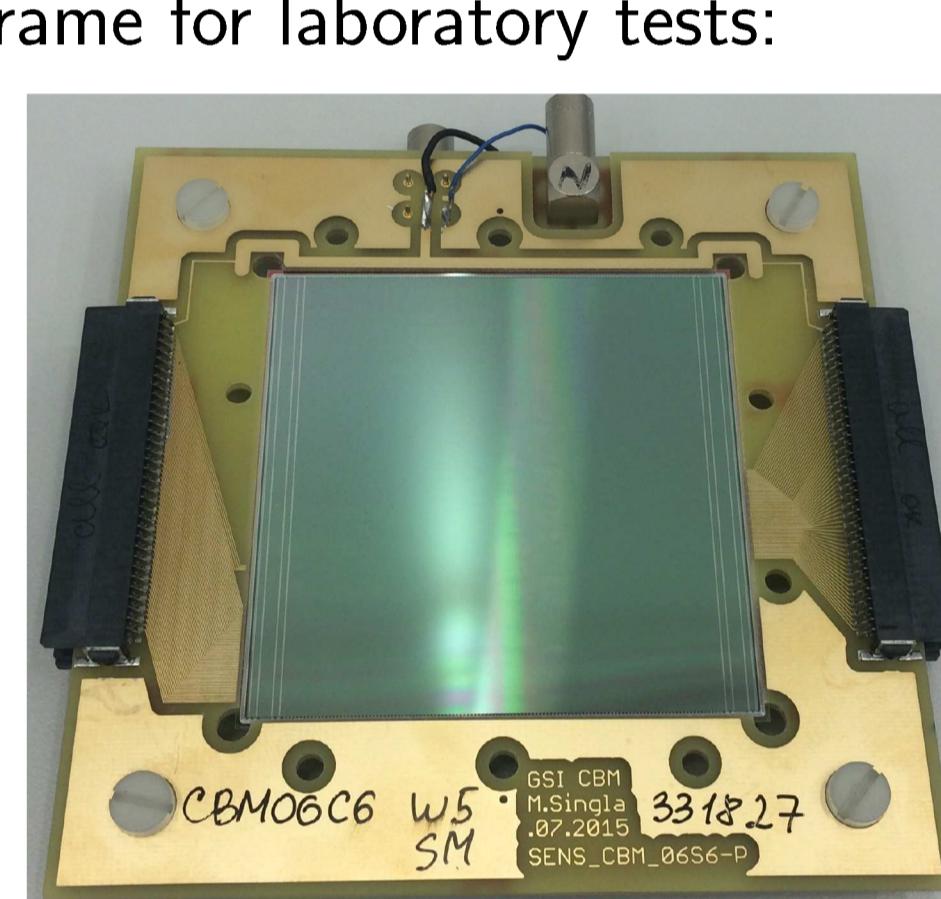
### Read-out electronics

- self-triggering mode
- signal shaping time  $< 20\text{ ns}$
- signal to noise ratio  $\simeq 15$  for non-irradiated sensors
- block-scheme of the read-out ASIC:

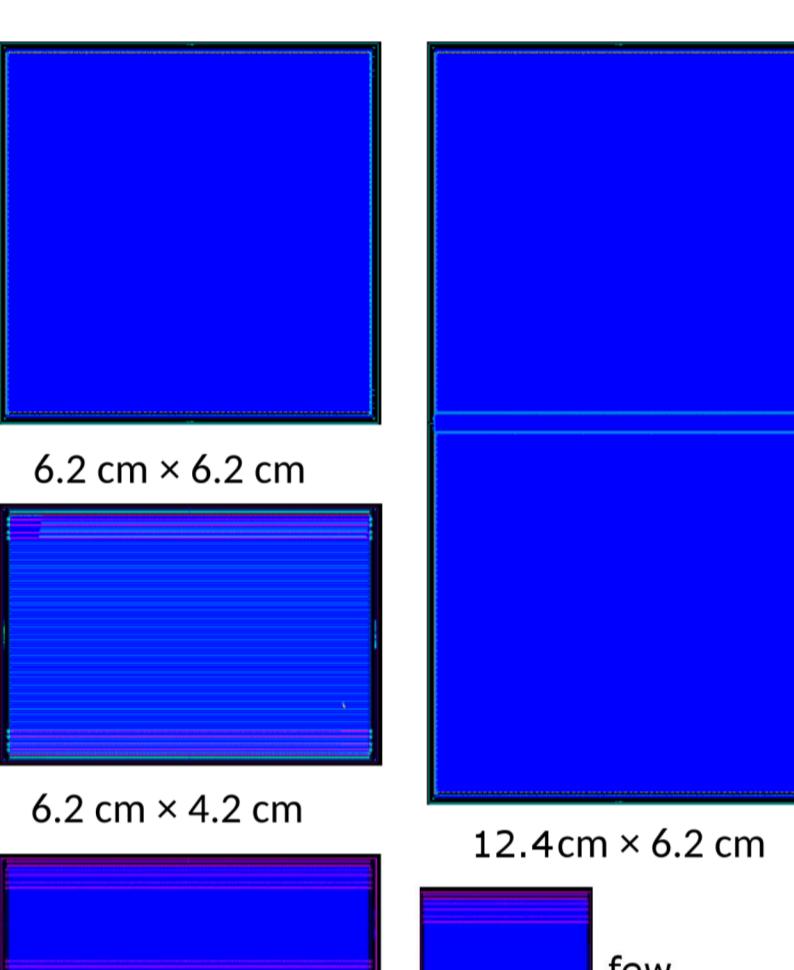


### Double-sided n-type silicon sensors

- $58\text{ }\mu\text{m}$  pitch
- 1024 strips per sensor
- AC-coupling, aluminium strips for r/o
- $7.5^\circ$  stereo angle for p-side (suppression of the ghost track rate)
- Sensor inside a sandwich PCB frame for laboratory tests:

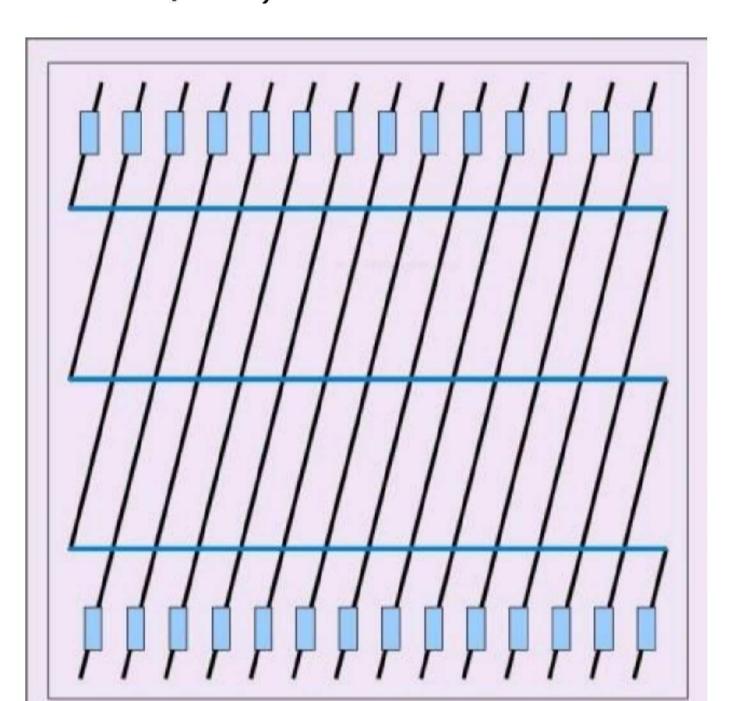


### VI generation of prototypes

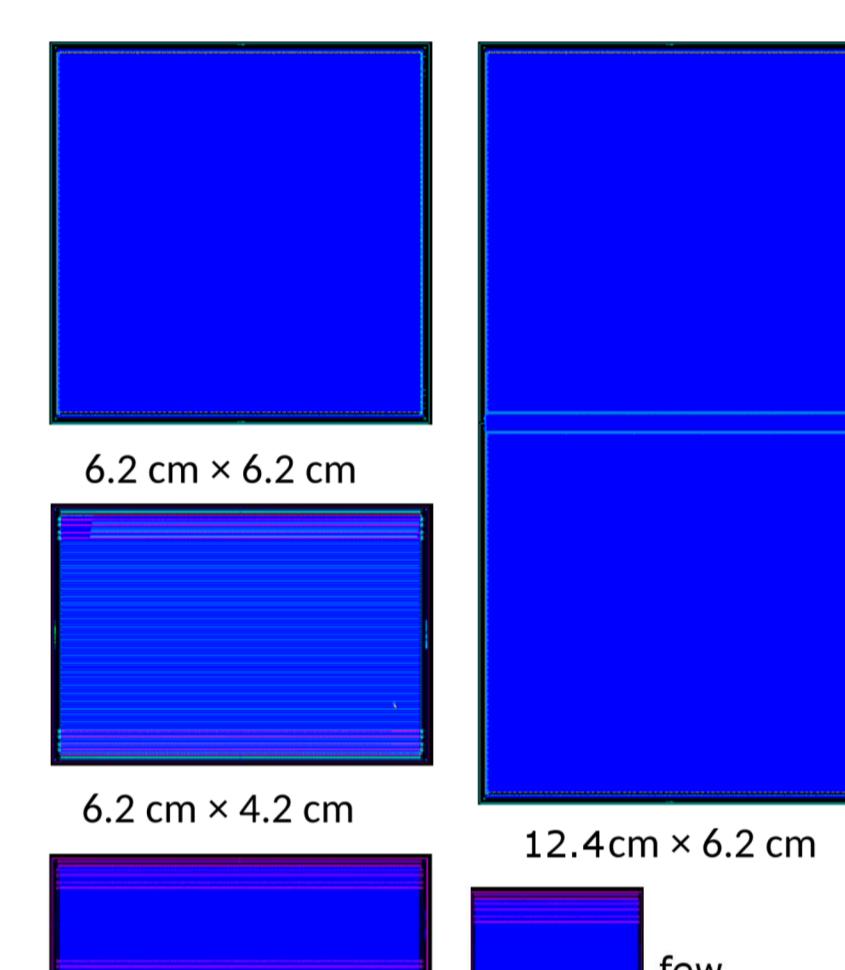


### Variety of silicon sensors to be tested:

- by vendors:
  - Hamamatsu ( $\simeq 320\text{ }\mu\text{m}$  thick)
  - CiS ( $\simeq 290\text{ }\mu\text{m}$  thick)
- routing line connection:
  - microcable (40  $\mu\text{m}$  thick polyimide and 20  $\mu\text{m}$  thick Al wires)
- double metalisation ( $\text{SiO}_2$  0.25  $\mu\text{m}$  and Al lines  $\sim 20\text{ }\mu\text{m}$ )



## Silicon sensor types



- radiation tolerance up to  $10^{14}\text{ n}_{\text{eq}}/\text{cm}^2$
- signal transfer to r/o electronics by microcable (polyimide 10  $\mu\text{m}$ , aluminium 14  $\mu\text{m}$  thick)

## Prototype tests and quality assurance

### R&D activities

- Signal induction sources for lab tests:
  - $\beta, \gamma$ -source radiation
  - infrared 1060 nm laser radiation
- R/O electronics:
  - nXYTER based FEBs



### QA for the mass production stage

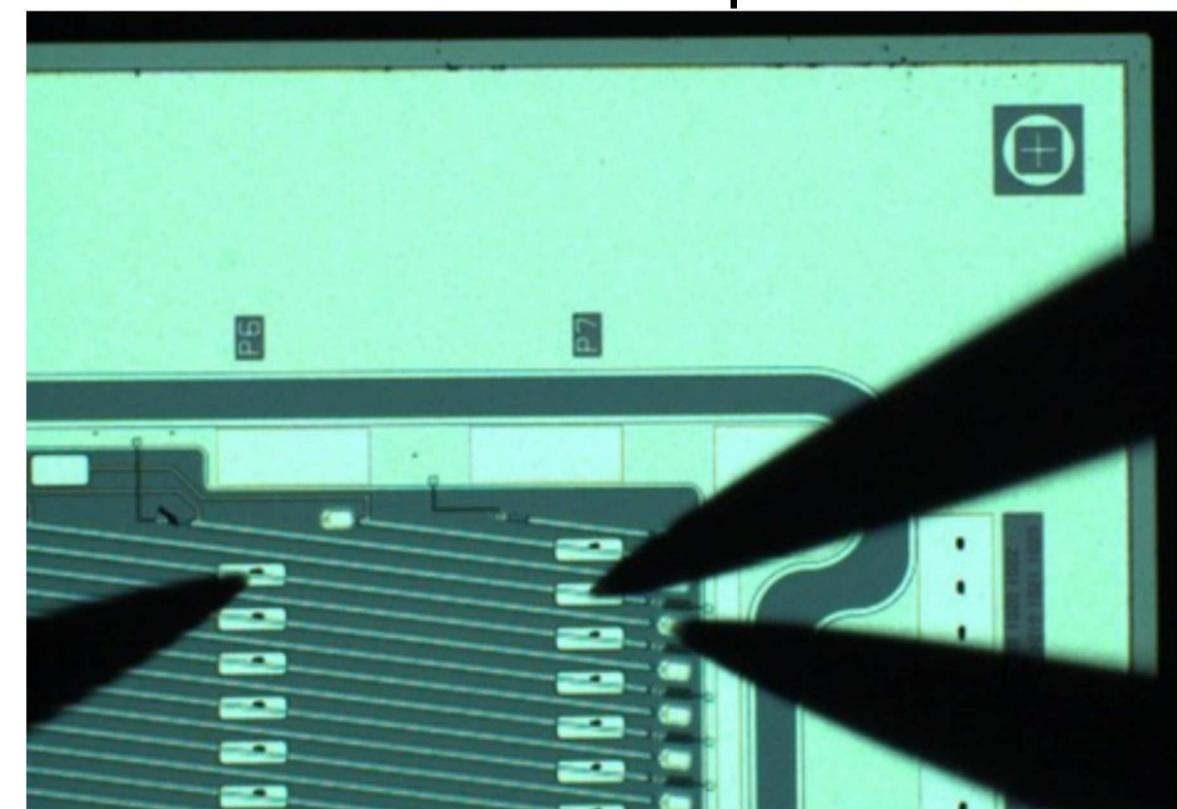


Workshop on Quality Assurance for the STS at Univ. Tübingen 28-29 January 2016

### Optical quality assurance



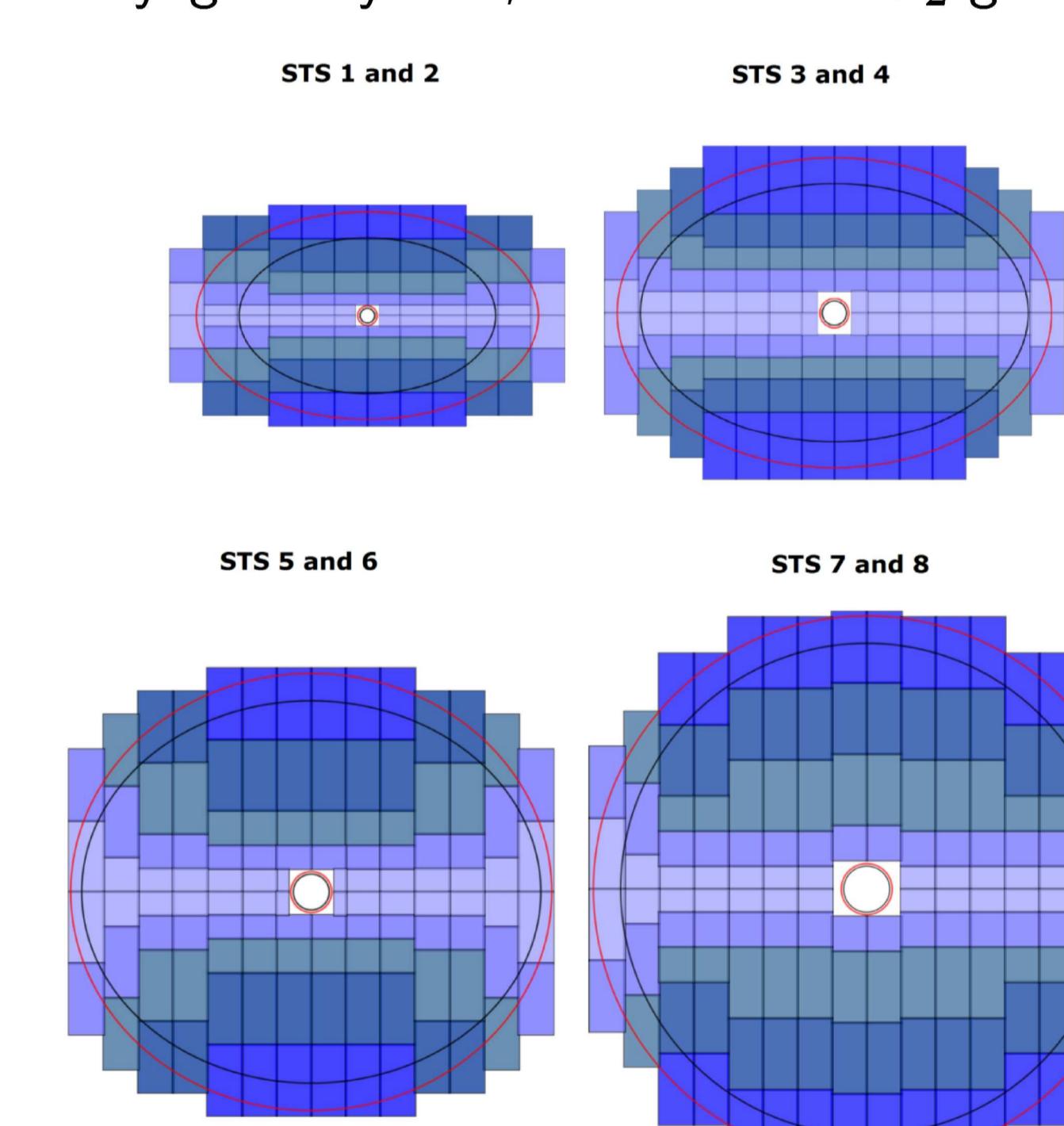
### Electrical tests with a probe station



### Measurements performed by vendors

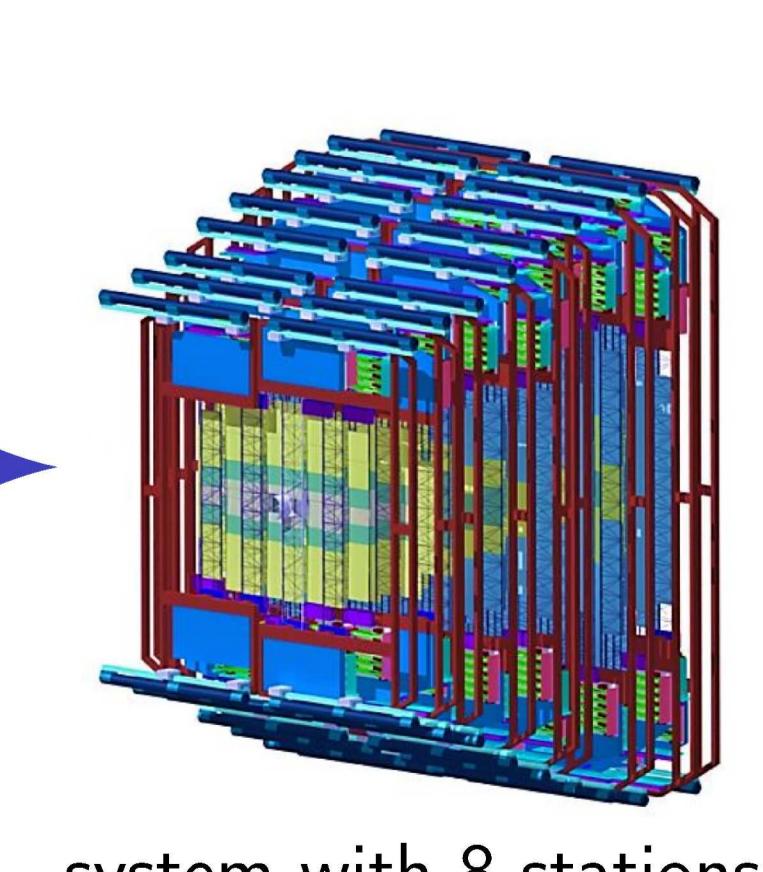
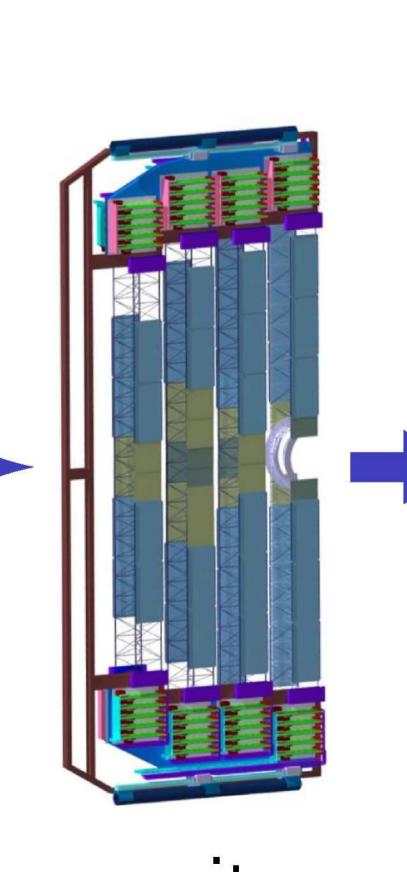
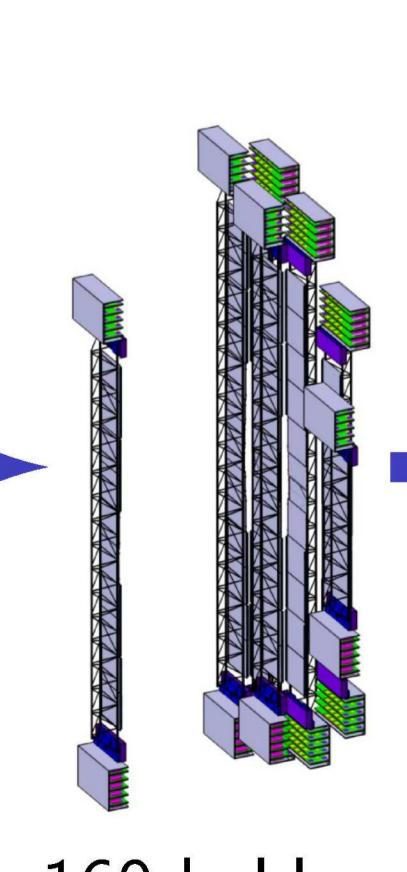
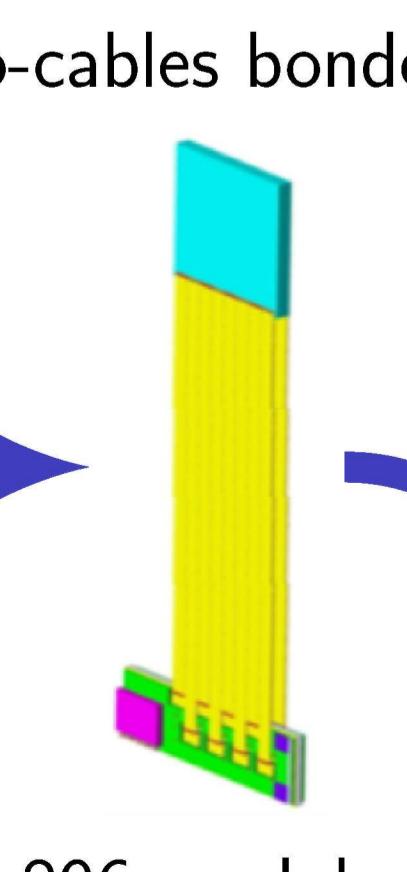
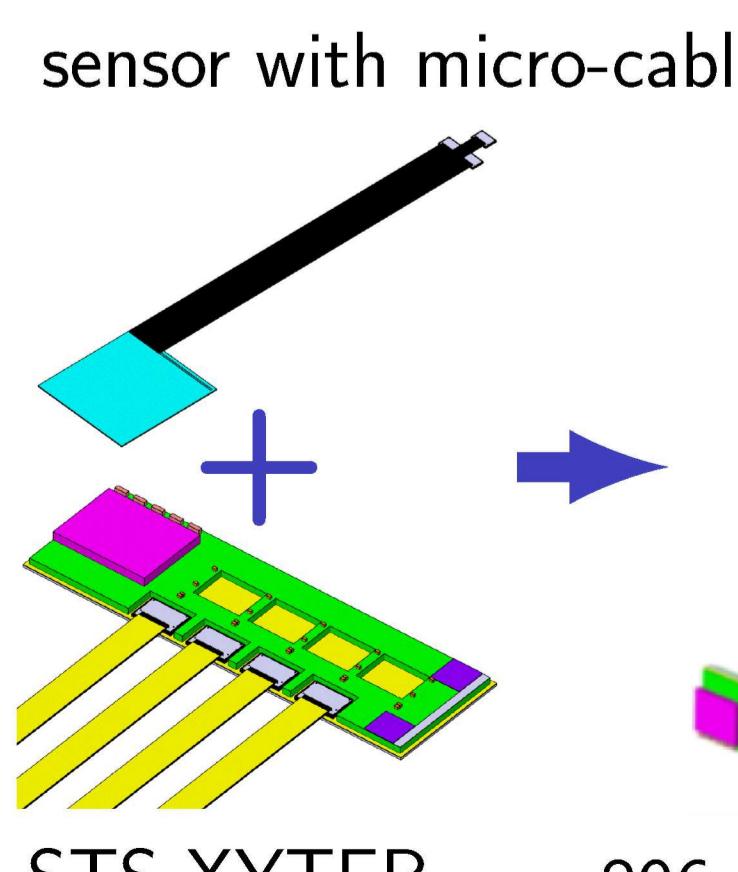
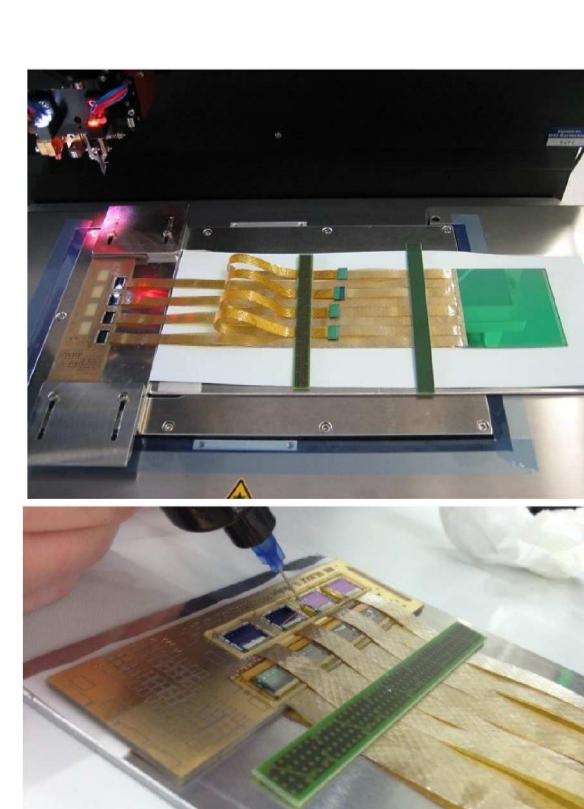
## Module and station assemblies

- Stations arranged in 4 duplets
- Cryogenic system, cooled with  $\text{CO}_2$  gas



- 8 tracking stations between 0.3 m and 1 m downstream the target
- Strips lengths — 2 cm, 4 cm, 6 cm, 12 cm
- Granularity according to the hit densities
- Components:
  - 160 ladders (17 types)
  - 896 modules
  - 1220 sensors
  - 14144 chips
  - $1.8 \times 10^6$  r/o channels

## System integration



### Challenging task of the low-mass tracker

- severe radiation environment
  - high signal/noise requirements
  - fast detectors/fast electronics
  - Studies of preferable sensor types
  - Tools for the QA under development
- STS project participants — about hundred researchers from 15 institutes in Germany, Poland, Russia and Ukraine
- 2017 – sensor serial production
  - 2020 – STS assembled

